

SN54S260, SN74S260 DUAL 5-INPUT POSITIVE-NOR GATES

SDLS208

DECEMBER 1983 — REVISED MARCH 1988

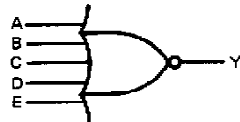
- Package Options Include Ceramic Chip Carriers and Flat Packages in Addition to Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

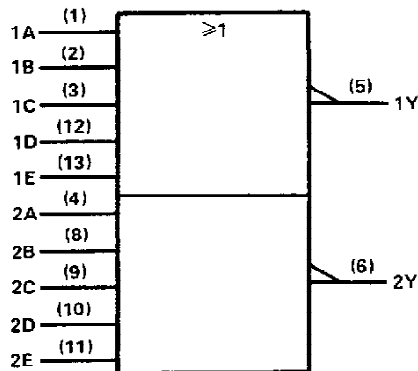
These devices contain two independent 5-input positive -NOR gates. They perform the Boolean function $Y = A + B + C + D + E$ in positive logic.

The SN54S260 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74S260 is characterized for operation from 0°C to 70°C .

logic diagram (each gate)

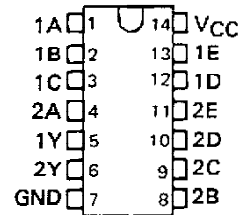


logic symbol†

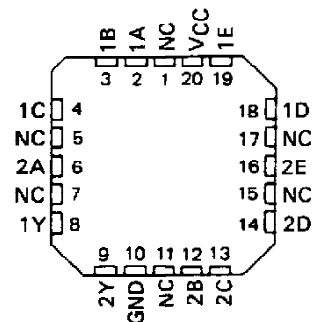


†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

SN54S260 . . . J OR W PACKAGE
SN74S260 . . . D OR N PACKAGE
(TOP VIEW)



SN54S260 . . . FK PACKAGE
(TOP VIEW)



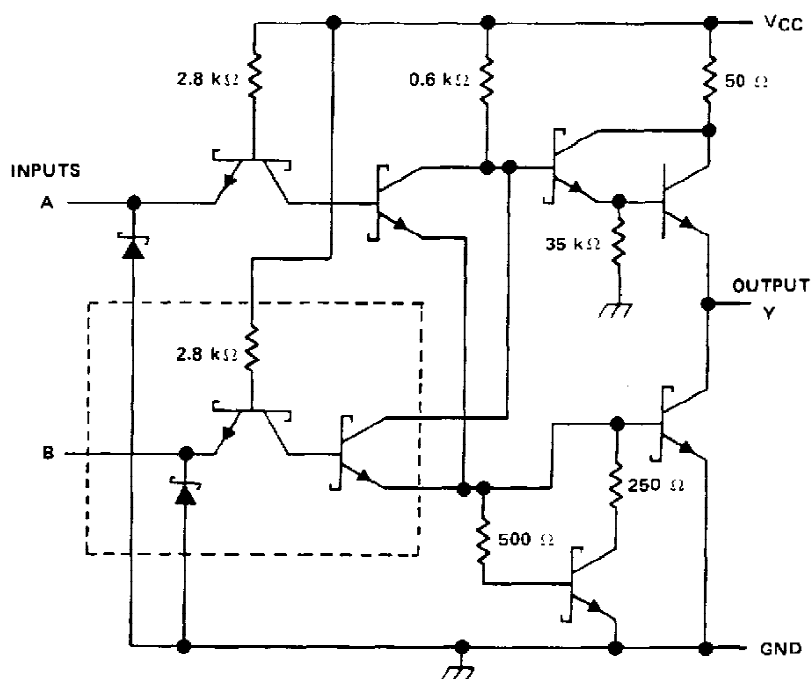
NC - No internal connection

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75285

schematic (each gate)



The portion of the schematic within the dashed-line is repeated for each additional input.

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	5.5 V
Operating free-air temperature range: SN54'	-55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

SN54S260, SN74S260

DUAL 5-INPUT POSITIVE-NOR GATES

recommended operating conditions

		SN54S260			SN74S260			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			-1			-1	mA
I_{OL}	Low-level output current			20			20	mA
T_A	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †	SN54S260			SN74S260			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	$V_{CC} = \text{MIN.}, I_I = -18 \text{ mA}$		-1.2			-1.2		V
V_{OH}	$V_{CC} = \text{MIN.}, V_{IL} = 0.8 \text{ V}, I_{OH} = -1 \text{ mA}$	2.5	3.4		2.7	3.4		V
V_{OL}	$V_{CC} = \text{MIN.}, V_{IH} = 2 \text{ V}, I_{OL} = 20 \text{ mA}$			0.5			0.5	V
I_I	$V_{CC} = \text{MAX.}, V_I = 5.5 \text{ V}$			1			1	mA
I_{IH}	$V_{CC} = \text{MAX.}, V_{IH} = 2.7 \text{ V}$			50			50	µA
I_{IL}	$V_{CC} = \text{MAX.}, V_{IL} = 0.8 \text{ V}$			-2			-2	mA
$I_{OS}§$	$V_{CC} = \text{MAX.}$	-40		-100	-40		-100	mA
I_{CCH}	$V_{CC} = \text{MAX.}, V_I = 0 \text{ V}$		17	29		17	29	mA
I_{CCL}	$V_{CC} = \text{MAX.}, \text{ See Note 2}$		26	45		26	45	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

NOTE 2: One input at 4.5 V, all others at GND.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Any	Y	$R_L = 280 \Omega, C_L = 15 \text{ pF}$		4	5.5	ns
t_{PHL}					4	6	ns

NOTE 3: See General Information Section for load circuits and voltage waveforms.



POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN54S260J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54S260J
SN54S260J.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54S260J
SN74S260D	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	0 to 70	S260
SN74S260DR	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	S260
SN74S260DR.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	S260
SN74S260N	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74S260N
SN74S260N.A	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74S260N
SNJ54S260J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54S260J
SNJ54S260J.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54S260J
SNJ54S260W	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54S260W
SNJ54S260W.A	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54S260W

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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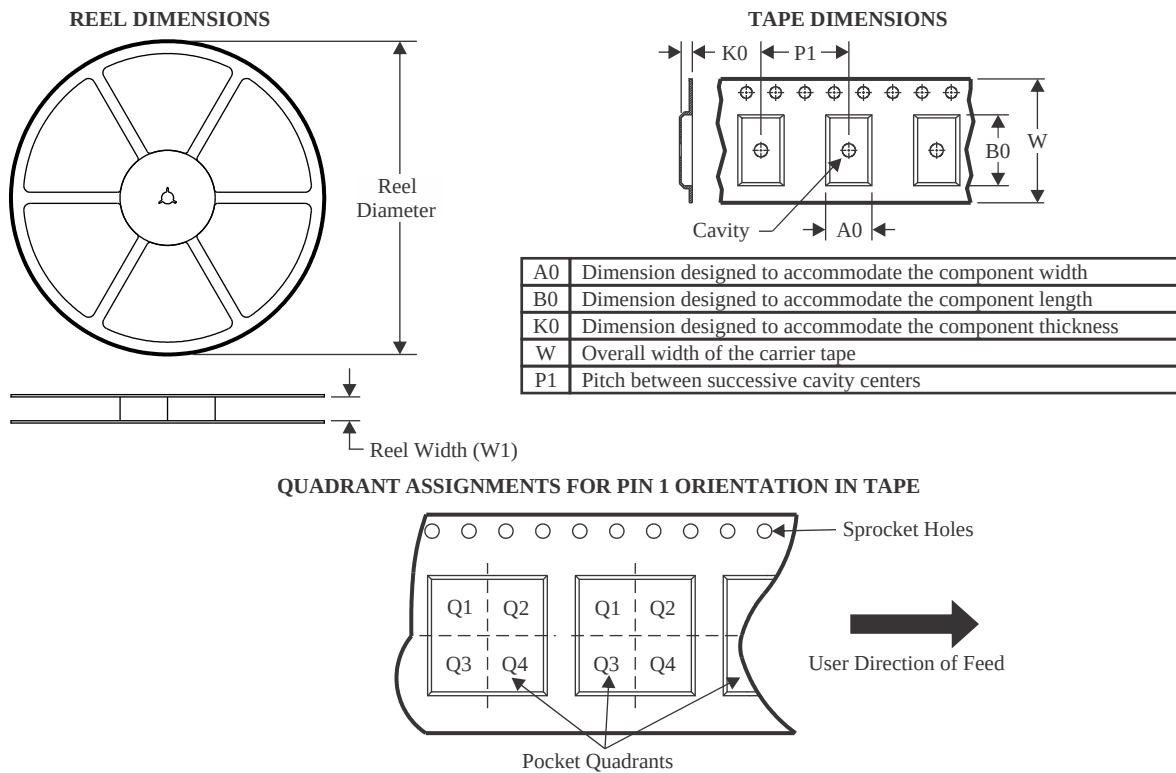
OTHER QUALIFIED VERSIONS OF SN54S260, SN74S260 :

- Catalog : [SN74S260](#)
- Military : [SN54S260](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

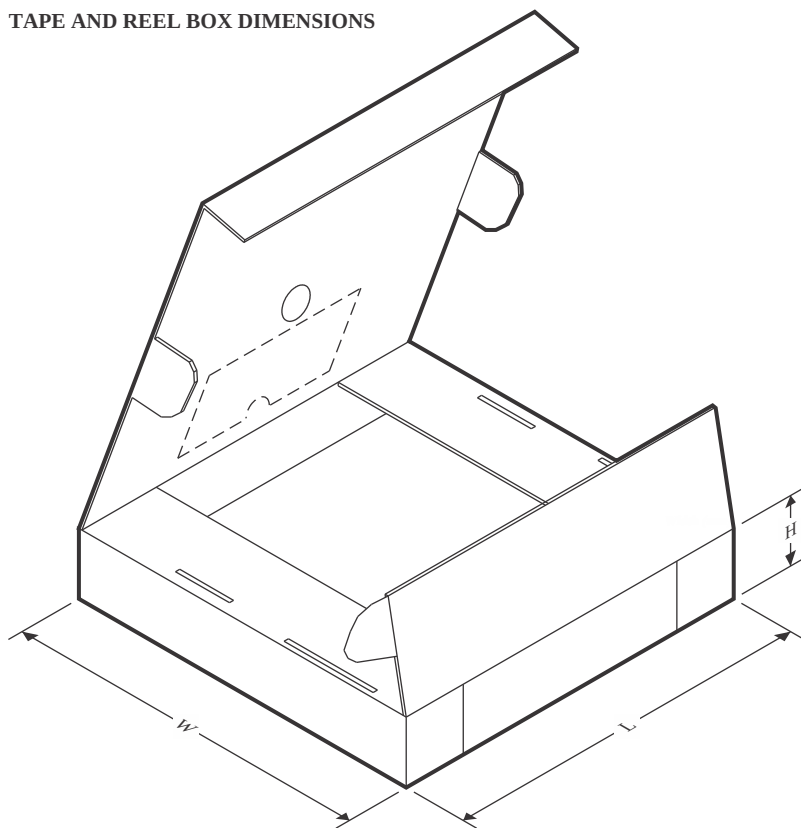
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74S260DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

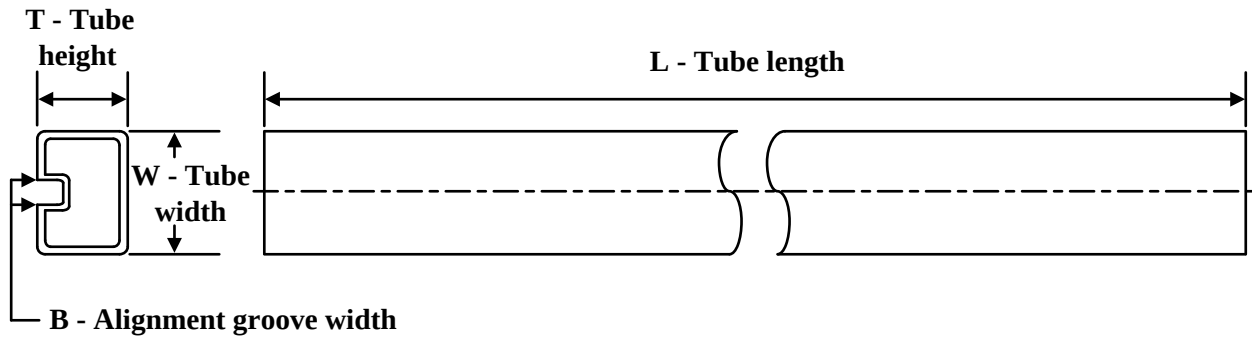
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

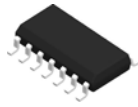
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74S260DR	SOIC	D	14	2500	353.0	353.0	32.0

TUBE

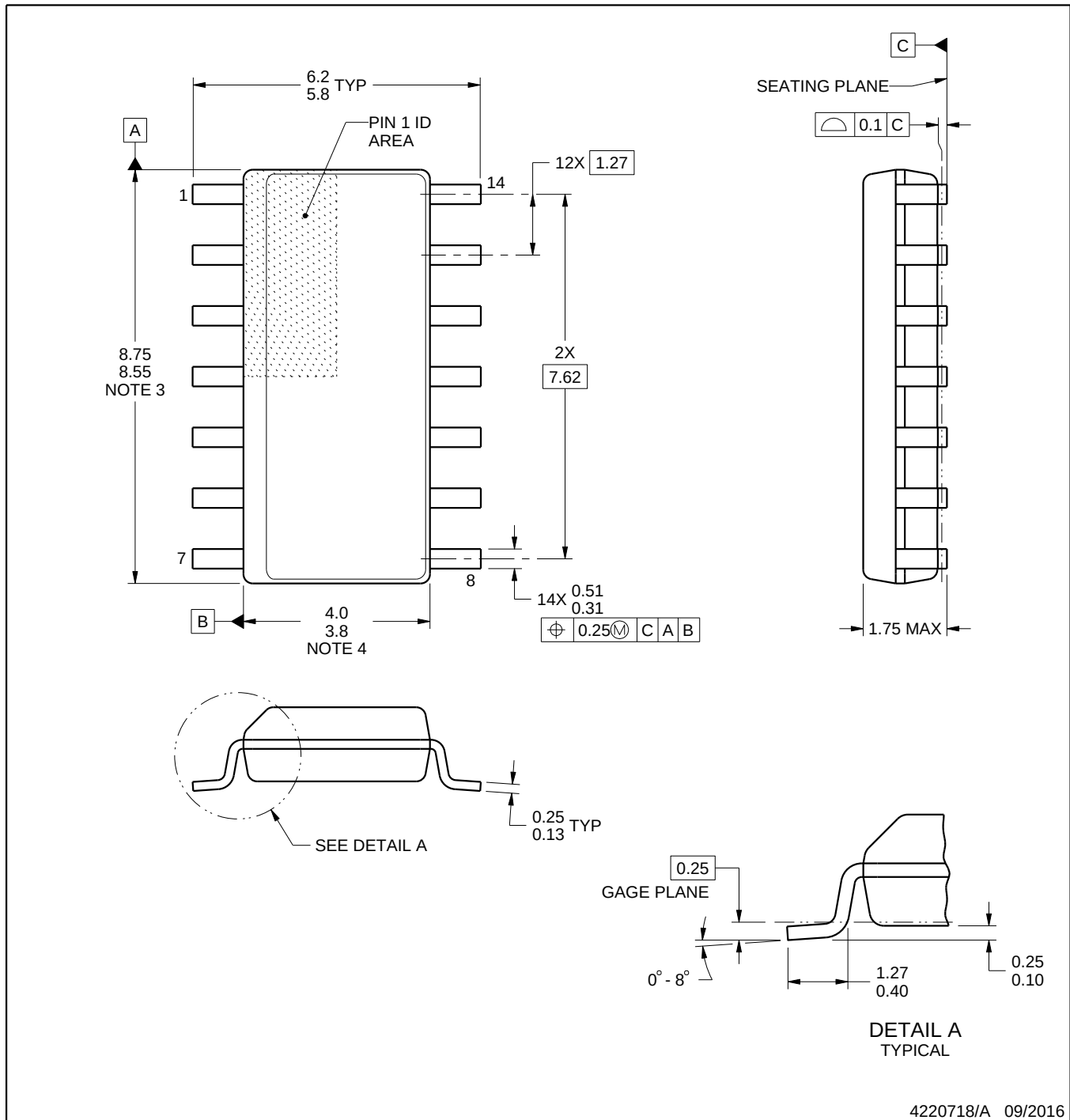


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74S260N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S260N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S260N.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74S260N.A	N	PDIP	14	25	506	13.97	11230	4.32

D0014A**PACKAGE OUTLINE****SOIC - 1.75 mm max height**

SMALL OUTLINE INTEGRATED CIRCUIT

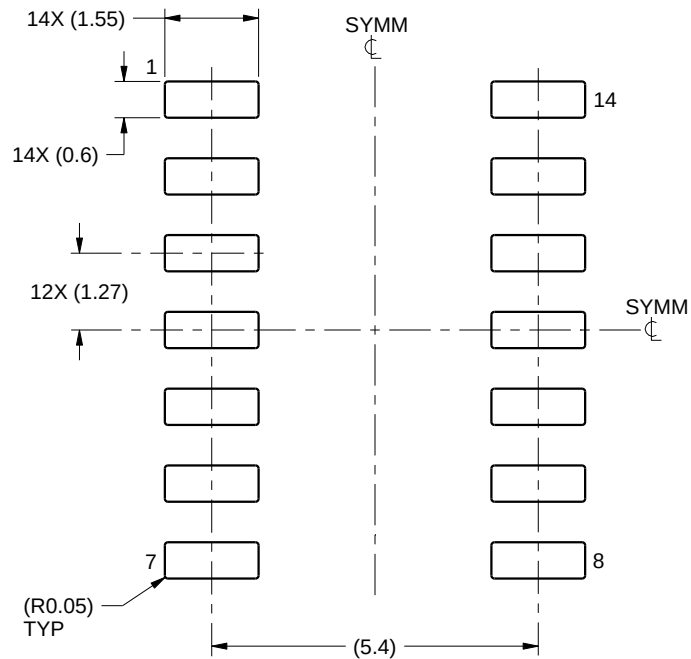


EXAMPLE BOARD LAYOUT

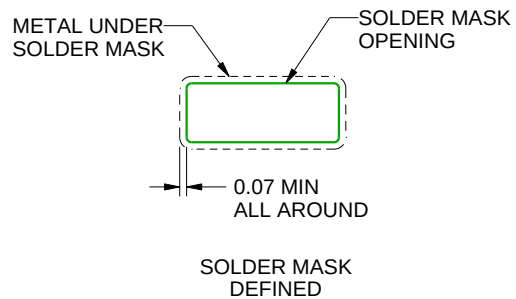
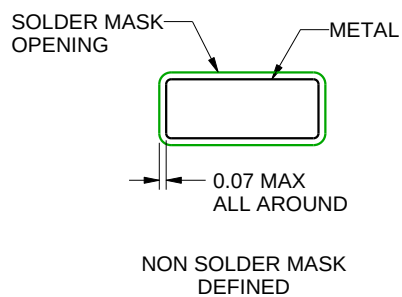
D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

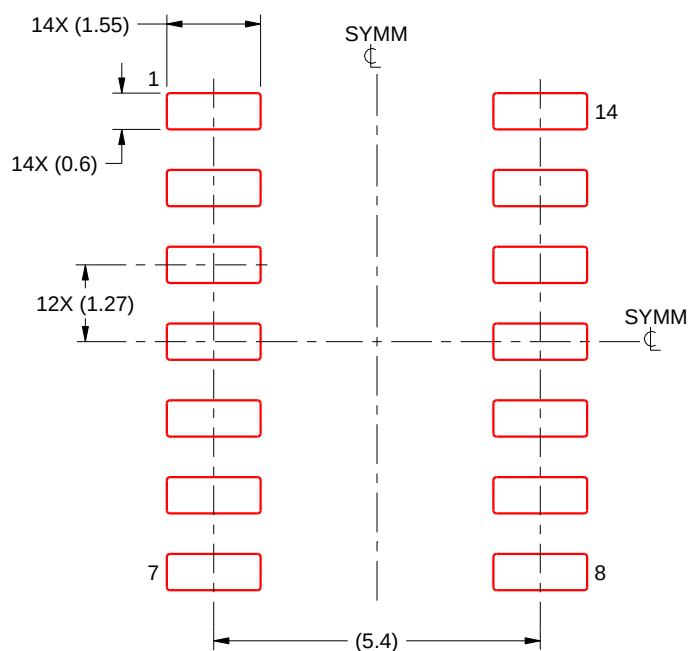
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

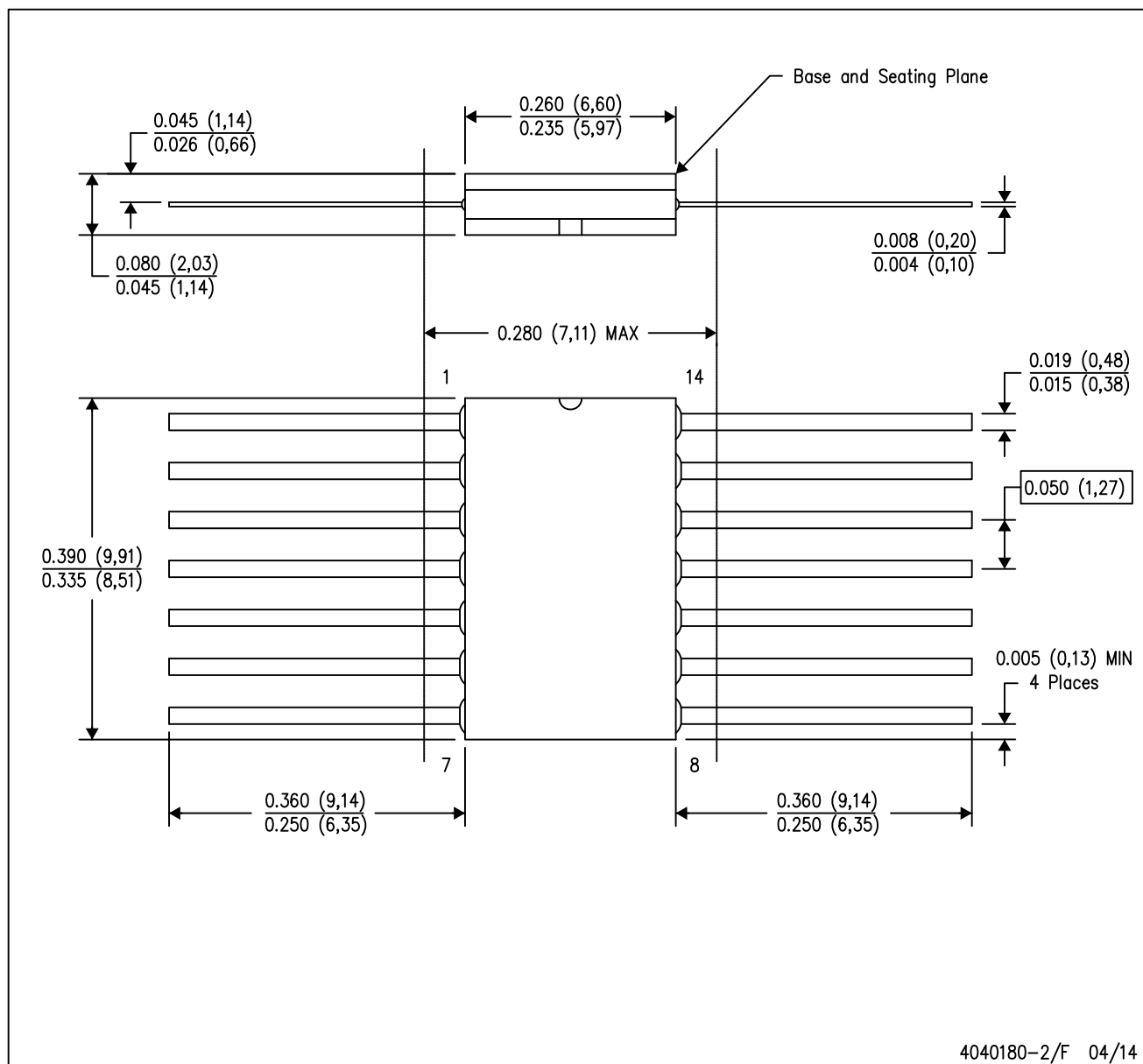
4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



NOTES:

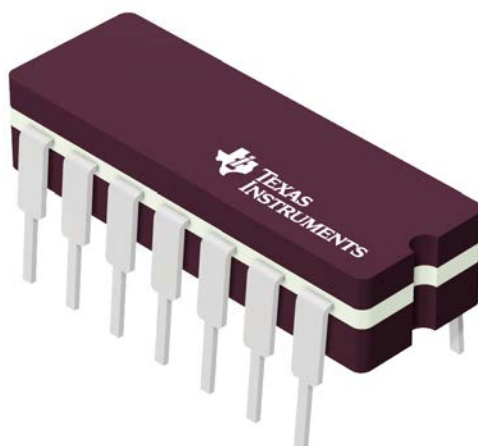
- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within MIL STD 1835 GDFP1-F14

J 14

GENERIC PACKAGE VIEW

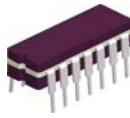
CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE

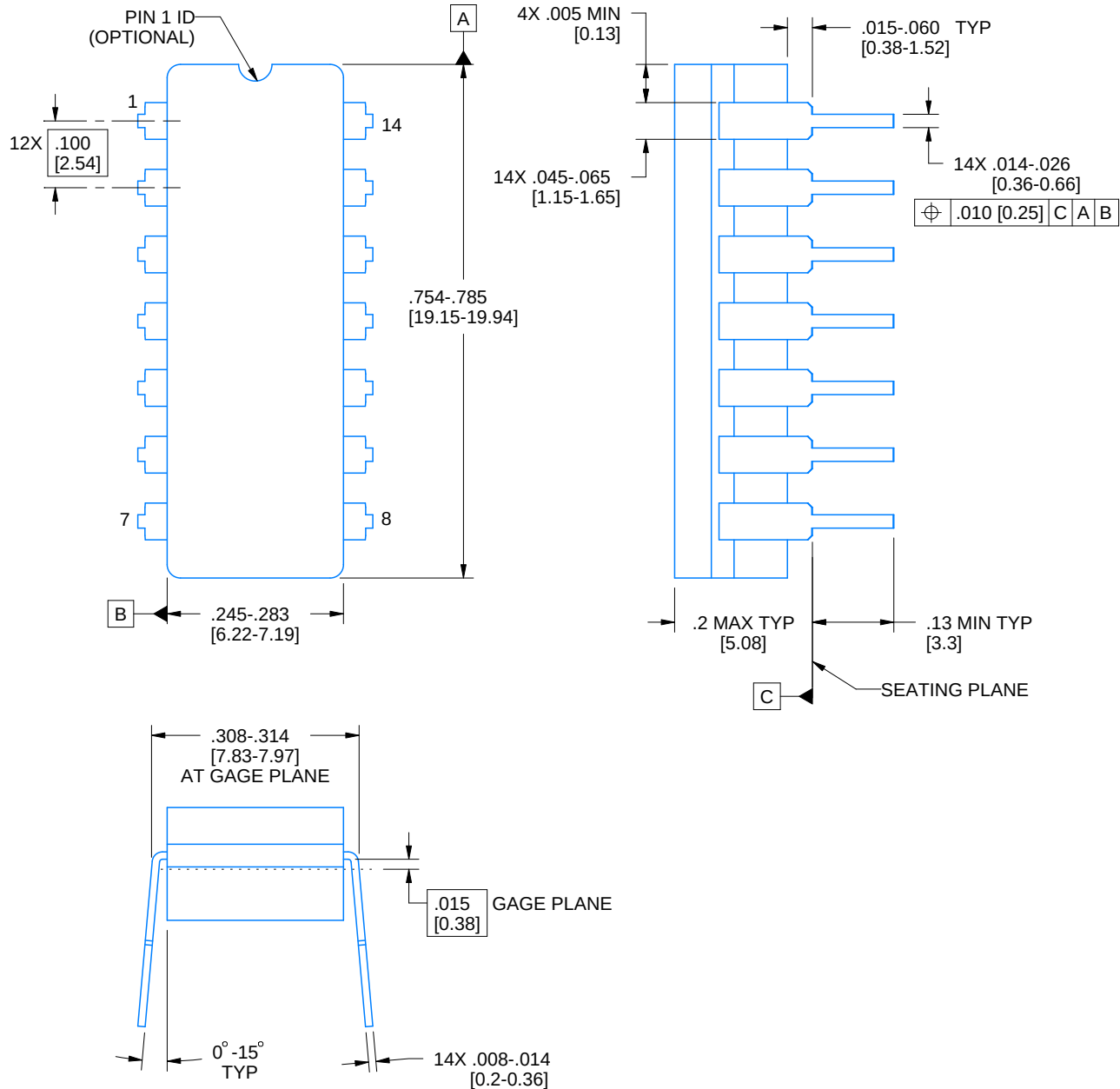


Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

J0014A**PACKAGE OUTLINE****CDIP - 5.08 mm max height**

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.



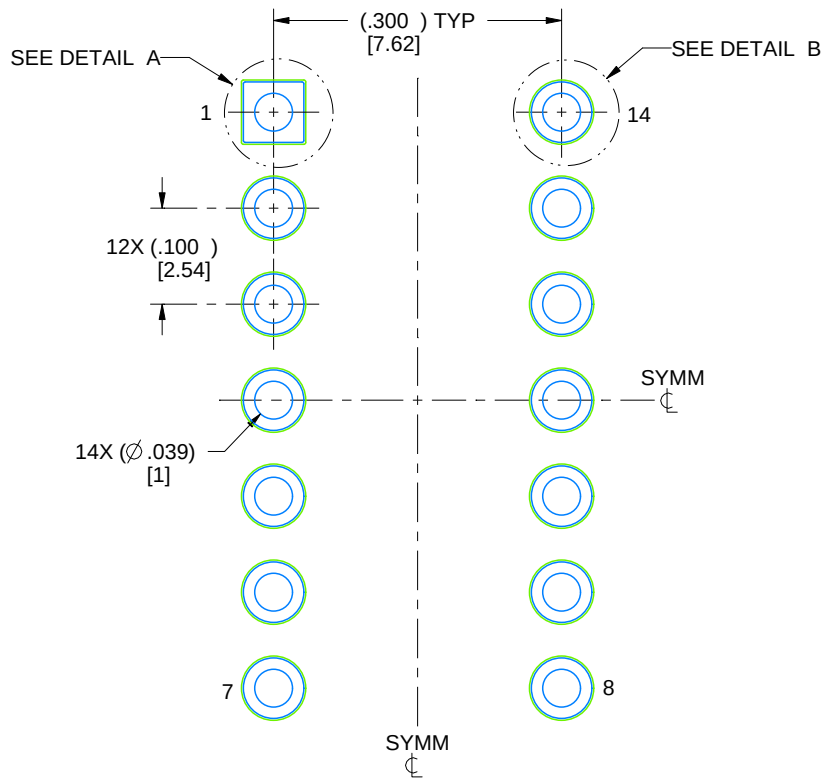
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EXAMPLE BOARD LAYOUT

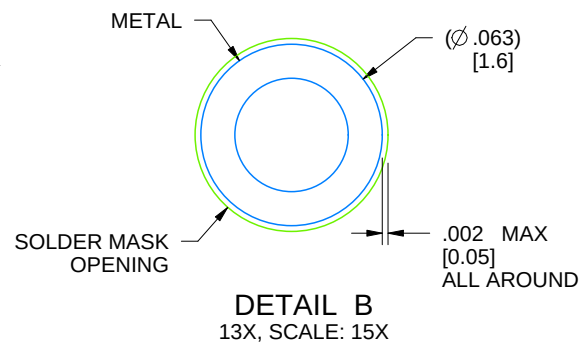
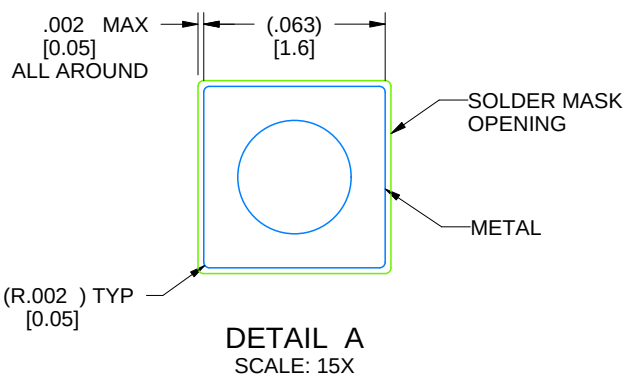
J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X

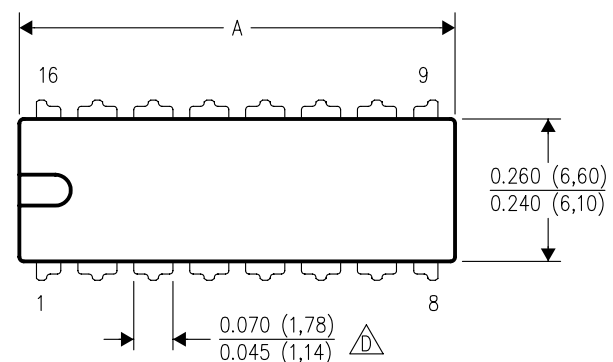


4214771/A 05/2017

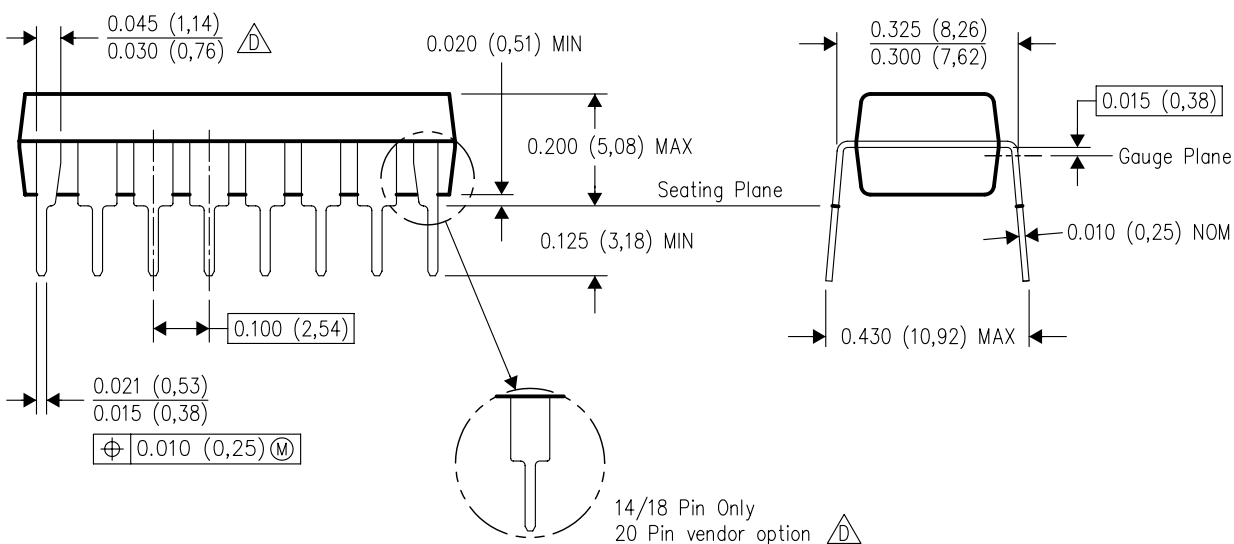
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

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